

9 SPACES @ 4.0 = 36.0

4.0

19

A

1.6 SHIELD CONTACT AREA

37.95 MAX.

2.0

18 SPACES @ 2.0 = 36.0

9 SPACES @ 4.0 = 36.0

2.0

4 SPACES @ 2.0 = 8.0

1.5

EDGE OF P. C. BOARD

21.0

8.8

11.40

3.7

3.3

2.0

10.8

5 SPACES @ 2.00 = 10.00

4 SPACES @ 2.0 = 8.0

13.85

10.85

4.93 REF

3.7 REF

9.6

11.4

ACTION PIN AREA

SECTION A-A
ROTATED 90° CW

1

GENERAL PLATING SPECIFICATION: UNDERPLATING (ENTIRE CONTACT): 1.27µm NICKEL MIN. AND ACTION PIN: 0.5µm TIN MIN. FOR PLATING OF MATING SURFACES SEE APPLICABLE SPECIFICATION REFERENCE FOR EACH DASH NUMBER.

2

CONFORMS TO ALL TESTING ACCORDING IEC 61076-4-101 PERFORMANCE LEVEL 2.

3

CONFORMS TO ALL TESTING ACCORDING IEC 61076-4-101 PERFORMANCE LEVEL 1.

4

MATERIAL:
CONTACT: PHOSPHOR BRONZE.
HOUSING: GLASS-FILLED POLYESTER.

5

CONNECTOR MARKED WITH PART NUMBER AND DATE CODE. ADDITIONAL CHARACTERS OR MARKINGS, AS WELL AS THE LOCATION OF THE MARKINGS, MAY BE ADDED FOR TRACEABILITY BASED UPON MANUFACTURERS DISCRETION.

6

PLATED-THROUGH HOLES AT 2x2mm SQUARE GRID PATTERN DEFINED BY CONTACT LAYOUT.

7

CONNECTOR LUBRICATED WITH TELCORDIA APPROVED LUBRICANT.

8

10 PLATED THROUGH HOLES FOR UPPER SHIELD, ROW F.

9

SHIELD MOUNTED TO CONNECTOR WITH DOUBLE SIDED ADHESIVE TAPE OR ADHESIVE.

10

CONNECTOR TESTED AND QUALIFIED AGAINST TELCORDIA GR-1217-CORE QUALITY LEVEL III, CENTRL OFFICE APPLICATIONS

11

CONNECTOR TESTED AND QUALIFIED AGAINST TELCORDIA GR-1217-CORE QUALITY LEVEL III, UNCONTROLLED ENVIRONMENT APPLICATIONS

12

OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

RECOMMENDED PCB-HOLE LAYOUT
COMPONENT SIDE SHOWN

SCALE 2.5:1

PLATED THRU HOLES PARAMETERS

REFERENCE APPLICATION SPECIFICATION

1

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Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9